

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	108	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 17:34
L2	264	257/E33.068	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 17:36
L3	1693	257/680	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 17:37
L4	5386	257/98	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 18:04
L5	4289	257/99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 18:18
L6	2210	257/100	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 18:41
L9	7	("4970566"   "5055893"   "5162878"   "5358880"). PN. OR ("5710441"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/03/03 18:55

L12	2009	257/431	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 19:01
L13	15	("20020053742"   "20040042707"   "5501989"   "5589694"   "5744822"   "5821597"   "6383835"   "6459132"   "6720576"   "6747290"   "6777746"   "7030551"   "7042052"   "7042099"   "7068246").PN. OR ("7335951").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/03/03 19:04
L14	1231	(optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate	USPAT	OR	ON	2010/03/03 19:16
L15	590	(optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (conduct\$3 or wir\$3 or metal\$3)	USPAT	OR	ON	2010/03/03 19:17
L16	2903	257/432	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 19:20
L17	4	("20030071338"   "20050103987"   "6774499"   "7102239"). PN. OR ("7446307"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/03/03 19:20
L18	5	("2003/0071338").URPN.	USPAT	OR	OFF	2010/03/03 19:23

L19	3	("20060267125"   "6646289"   "6767753"). PN. OR ("7271024"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2010/03/03 19:27
L20	1	("2006/0267125").URPN.	USPAT	OR	OFF	2010/03/03 19:27
L21	2153	257/433	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 19:39
L22	12	257/E27.128	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:00
L23	63	257/E27.137	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:01
L24	58	257/E27.161	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:02
L25	5	257/E27.163	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:03
L26	1259	257/434	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:04
L27	3314	428/138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:07

L28	22	257/E31.118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:09
L29	18	257/E31.13	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/03/03 20:11
S1	15	"4,936,808".pn. or "6,412,971".pn. or "6,373,188".pn. or "6,184,544".pn. or "6,335,545".pn. or "20040005728" or "20030160258" or "4,005,457".pn. or "20040041159" or "20020137245" or "6,291,841".pn. or "5,307,360".pn. or "20020096254"	US-PGPUB; USPAT	OR	OFF	2009/12/05 21:31
S2	7098	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (insulat\$3 or dielectric) and substrate	USPAT	OR	ON	2009/12/05 22:08
S3	1157	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate	USPAT	OR	ON	2009/12/05 22:09
S4	14	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or	USPAT	OR	ON	2009/12/05 22:25

		conductive or metal\$2) near (layer or film)				
S5	42	(soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:30
S6	28	S5 not S4	USPAT	OR	ON	2009/12/05 22:30
S7	43	(optoelectronic or light or optical or LED or sensor) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:37
S8	1	S7 not S5	USPAT	OR	ON	2009/12/05 22:37
S9	43	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:38

S10	51	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2)	USPAT	OR	ON	2009/12/05 22:38
S11	9	S10 not S5	USPAT	OR	ON	2009/12/05 22:38
S12	19	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (pad)	USPAT	OR	ON	2009/12/05 22:41
S13	405	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/05 22:49
S14	1	("2004/0041159").URPN.	USPAT	OR	OFF	2009/12/05 23:14

S15	9	("5261013"   "5323084"   "5656847"   "6153448"   "6482664"   "6504180"   "6570180"   "6593598"   "6744194").PN. OR ("7078737").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/05 23:16
S16	543	(optoelectronic or light or optical or LED or sensor or emitt\$3) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/05 23:17
S17	138	S16 not S13	USPAT	OR	ON	2009/12/05 23:17
S18	546	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:38
S19	547	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:38

S20	3508	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:38
S21	422	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate with pads and (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side)	USPAT	OR	ON	2009/12/07 00:39
S22	1	"20070190290"	US-PGPUB; USPAT	OR	ON	2009/12/07 01:29
S23	2	257/E	US-PGPUB; USPAT	OR	ON	2009/12/07 01:30
S24	101	257/E31.117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:30
S25	228	257/E33.068	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:31
S26	1656	257/680	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:33



S27	5017	257/98	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:35
S28	4049	257/99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 01:43
S29	2106	257/100	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:02
S30	1951	257/431	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:20
S31	2761	257/432	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:32
S32	2086	257/433	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 02:51
S33	836	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments or particles or powder) with (color\$3 or absorb\$3)	USPAT	OR	ON	2009/12/07 02:53
S34	335	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments) with (color \$3 or absorb\$3)	USPAT	OR	ON	2009/12/07 02:53

S35	59	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with height with "0.4" near ("mm")	USPAT	OR	ON	2009/12/07 02:59
S36	114	(optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with height with "0.1" near ("mm")	USPAT	OR	ON	2009/12/07 03:02
S37	1221	257/434	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 03:11
S38	51	(optoelectronic or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments) with (color\$3 or absorb \$3)	USPAT	OR	ON	2009/12/07 03:13
S39	3263	428/138	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/07 03:16
S40	1925	257/685	USPAT	OR	OFF	2009/12/07 15:55

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